Ankit More

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RESEARCH

Digital, Analog and Mixed Signal Integrated Circuits, Radio Frequency Integrated Circuits (RFIC),

INTERESTS Low Power VLSI Circuits, 3-D ICs and Post-CMOS Interconnect, Network-on-chip (NoC).

EDUCATION \diamond **Ph.D., Electrical Engineering**, (September 2009 – current).

Drexel University, Philadelphia, PA.

Topic: Wireless interconnects for inter and intra-chip communication

♦ M.S., Electrical Engineering, GPA: 3.95 (Summa-cum-laude), (June 2009).

Drexel University, Philadelphia, PA. Concentration: Systems and Control

♦ **B.S., Electrical Engineering**, GPA: 3.95 (Summa-cum-laude), (June 2009).

Drexel University, Philadelphia, PA. Concentration: Advanced Electronics

PROFESSIONAL & Research Assistant and Teaching Assistant, (September 2009 – current)

EXPERIENCE

Department of Electrical and Computer Engineering

Drexel University, Philadelphia, PA

- Research Assistant in the VLSI Lab working on
 - VLSI design and
 - 3D electro-magnetic modeling.
- Teaching Assistant in the ECE Department for
 - Electrical Engineering Laboratory 3 (ECE-L 303) (Fall, AY 2009 2010).
 - Electrical Engineering Laboratory 4 (ECE-L 304) (Winter, Summer, AY 2009 2010).
- Introduction to Nuclear Reactor Theory (Spring, AY 2009 2010).

♦ Internship - Research and Development Engineering, (April 2008 – September 2008)

Siemens Energy and Automation, Spring House, PA, USA

- Developed automated software testing tools for distributed control systems software.
- Co-authored patent application for an expandable automated testing concept, awaiting filing of application.
- Assisted in Virtual Machine management using VMWare.

♦ Internship - Assistant Project Manager , (September 2006 – March 2007)

Maida Engineering Inc, Fort Washington, PA, USA

- Assisted in design of power distribution systems to manufacturing plants.
- Created two dimensional CAD layouts using AutoCAD for electrical systems according to the NEC.

SELECTED Wireless Interconnect Design, Drexel University

PROJECTS

- Design of on-chip antennas for inter and intra-chip communication for planar and 3D ICs.
- Design of integrated analog transceiver circuits.
- IC design in IBM 90 nm technology.
- Full-wave 3D Finite Element Method (FEM) electro-magnetic simulations.
- Simulation of leakage current, electro-magnetic compatibility and interference.

♦ Rotary Clock Custom Integrated Circuit, Drexel University

- Design of custom and regular rotary rings.
- IC design in AMI C5N 0.5 μm process using MOSIS fabrication process.

♦ Senior Design, Unmanned Aerial Vehicle (UAV), Drexel University

- Autonomous control for stable hover of miniature unmanned aerial vehicles.
- Designed a control system using embedded C code on Texas Instruments TMS320 DSP.
- Designed custom peripheral circuits for DSP isolation and sensor connection.
- Co-sponsored by the U.S. Army Research Lab and the MEM Department, Drexel University.

- PUBLICATIONS & Ankit More and Baris Taskin, Wireless Interconnects for Inter-tier Communication on 3-D ICs, Proceedings of the European Microwave Integrated Circuits Conference (EuMIC), September 2010.
 - ♦ Ankit More and Baris Taskin, Simulation Based Study of On-chip Antennas for a Reconfigurable Hybrid 3D Wireless NoC, Proceedings of the IEEE International SoC Conference (SOCC), September 2010.
 - ♦ Ankit More and Baris Taskin, Effect of EMI between Wireless Interconnects and Metal Interconnects on CMOS Digital Circuits, Proceedings of the Mediterranean Microwave Symposium (MMS), August 2010.
 - Ankit More and Baris Taskin, Simulation Based Feasibility Study of Wireless RF Interconnects for 3D ICs, Proceedings of the IEEE Computer Society Annual Symposium on VLSI (ISVLSI), July 2010.
 - Ankit More and Baris Taskin, Electromagnetic Compatibility of CMOS On-chip Antennas, Proceedings of the IEEE International Symposium on Antennas and Propagation (APS), July 2010.
 - Ankit More and Baris Taskin, Simulation Based Study of Wireless RF Interconnects for Practical CMOS Implementation, Proceedings of the System Level Interconnect Prediction (SLIP), June 2010.
 - Ankit More and Baris Taskin, Electromagnetic Interaction of On-Chip Antennas and CMOS Metal Layers for Wireless IC Interconnects, Proceedings of the IEEE/ACM Great Lakes Symposium on VLSI (GLSVLSI), May 2010.
 - Ankit More and Baris Taskin, Leakage Current Analysis for Intra-Chip Wireless Interconnects, Proceedings of the IEEE International Symposium on Quality Electronic Design (ISQED), pp. 49– 53, March 2010.
 - SKILLS & C, C++, SystemC, Basic Java, CLisp, XML, XSLT, JScript, VBScript
 - ♦ Cadence Virtuoso Suite, Spectre, PSpice Synopsys - Design Compiler, ICC Complier, HSpice
 - ♦ Ansoft High Frequency Structure Simulator (HFSS), Q3D extractor Agilent – Advanced Design Systems (ADS)
 - ♦ Matlab, Maple, Labview, AutoCAD, Quick Test Professional
 - ♦ LATEX, Office Suites
 - ♦ Unix, Linux, MS Windows

AWARDS

- ACADEMIC ♦ George Hill, Jr. Fellow, Drexel University, 2010 2011.
- $HONORS\ AND\ \ \, \diamond\ \, Freshman\ Design\ Fellow\ for\ the\ College\ of\ Engineering,\ Drexel\ University,\ 2010-2011.$
 - ♦ President, Drexel IEEE Graduate Forum, 2010 2011.
 - ♦ Graduated with 1st Honors (highest GPA among the graduating class) from the Department of Electrical and Computer Engineering, Drexel University, 2009.
 - ♦ Dean's List, College of Engineering, Drexel University, 2005 2009.
 - ♦ A.J. Drexel Academic Scholarship, Drexel University, 2005 2009.
 - ♦ John Raymond Vollmar Endowed Scholarship, Drexel University, 2007 2008.
 - ♦ Harry E. Muchnic Scholarship, Drexel University, 2008 2009.
 - ♦ Tau Beta Pi National Scholarship, 2008 2009.
 - ♦ Member, Tau Beta Pi, Engineering Honor Society.
 - ♦ Member, Eta Kappa Nu, Electrical Engineering Honor Society.

COURSEWORK

RELEVANT & CMOS VLSI Design, Computer Architecture, CAD for VLSI Design, Digital IC Design, RFIC Design, Stochastic Systems, Microwave Passive Systems, Microwave Active Systems, RF Electronics, Numerical Analysis Methods.

REFERENCES \diamond **Dr. Moshe Kam**

IEEE President Elect - 2010

Department Head and Robert Quinn Professor

Department of Electrical and Computer Engineering

Drexel University, Philadelphia, PA

E-mail: kam@minerva.ece.drexel.edu

♦ Dr. B.C. Chang

Professor, Department of Mechanical Engineering and Mechanics

Drexel University, Philadelphia, PA

E-mail: bchang@coe.drexel.edu

♦ Dr. Baris Taskin

Assistant Professor, Department of Electrical and Computer Engineering

Drexel University, Philadelphia, PA

E-mail: taskin@coe.drexel.edu